

Flexible Tape Electronics Packaging And Methods of Manufacture

Abstract of the Disclosure

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To decrease the weight and the thickness, and to increase the flexibility, of an electronics package, the package includes an integrated circuit (IC) mounted on a flexible tape substrate. In one embodiment, an IC is mounted on a flexible tape substrate using a ball grid array arrangement; however, other arrangements, including lead bonding, can be used. The flexible tape substrate can comprise conductive traces, vias, and patterns of lands on one or more layers. Methods of fabrication, as well as application of the flexible tape package to an electronic assembly, an electronic system, and a data processing system, are also described.

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